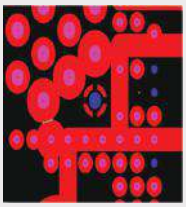
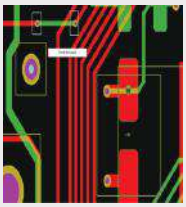
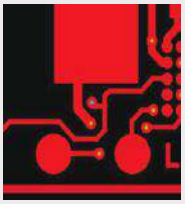
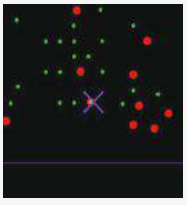
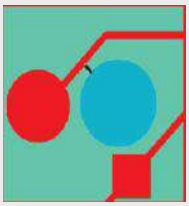
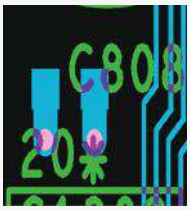
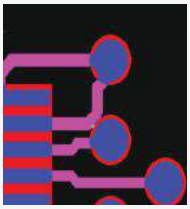
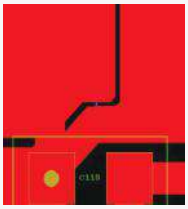
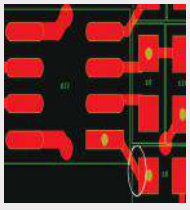
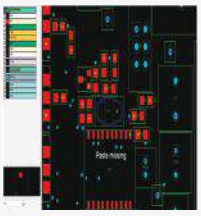
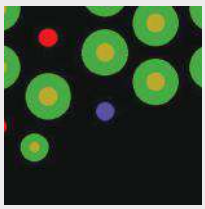
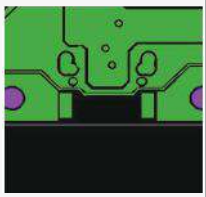
ID	ISSUES-CATEGORY	PRIORITY	IMAGE	X-LOCATION(")	Y-LOCATION(")	LAYERS	VALUE	ISSUE/ RECOMMENDATION	STATUS	CUSTOMER FEEDBACK
1	OPENS NETS	CRITICAL		3.425	-5.058464	L2;L2	0	THERMAL HAS BEEN ISOLATED FROM THE GROUND NET IN THIS AREA WHERE THE CLEARANCES AROUND THE PADS HAS CUT IT OFF, CREATING AN OPEN IN THE NET IN THE BOARD.KINDLY CHECK AND UPADATE	OPEN	
2	STARVED THERMAL VIAS	CRITICAL		0.815645	19.19986	L4;L4	0	STARVED THERMAL VIAS PREVENT PROPER HEAT CONTAINMENT AND MAY AFFECT QUALITY OF HOLE PLATING KINDLY CHECK	OPEN	
3	ASPECT RATIO	CRITICAL		0	0	AS PER THE PICTURE	-	6 MIL DRILL USED AS A MINIMUM DRILL SIZE AT TWO LOCATIONS ,WITH 6MIL DRILL & 2.5MM BOARD THICKNESS (ASPECT RATIO = 6MIL/98.4MILS= 16.3) ,AS PER STANDARDS FOR HIGHER YIELD ASPECT RATIO SHALL BE <= 10, 6MIL DRILL MAY CALL FOR HIGHER FABRICATION COST.	OPEN	
4	CLOSE PADS/TRACES	CRITICAL		2.533465	0.480315	TOP;BOTTOM	0.002	CLOSE PADS/TRACES MAY BRIDGE DURING IMAGING, PLATING OR SOLDERING, AND RESULT IN A DIRECT SHORT	OPEN	
5	STUBBED_VIA	HOT		0.314764	0.086413	D_TOP_L2 D_TOP_L2; TOP;L2	0.004	STUBBED VIAS CAN AFFECT SIGNAL PERFORMANCE, KINDLY CHECK	OPEN	
6	DRILL OVERLAPPING	HOT		0.467567	0.062992	D_L2_L3 D_L2_L3; D_TOP_L2	0	DUPLICATE VIA DRILLS WILL CAUSE DRILL BITS TO BREAK AND CAUSE SCRAP	OPEN	
7	SPACING	CRITICAL		0.446931	0.147897	L1;L1	0.0015	MINIMUM SPACING IS LESS THAN 4 MILS PRESENT IN THE BOARD BUT IN FAB DRAWING 4 MILS MENTIONED KINDLY CHECK.	OPEN	
8	WIDE TRACE NARROW PAD	HOT		0.446593	0.14618	TOP;TOP	0	A WIDE TRACE CONNECTED TO A NARROW PAD MAY CAUSE SOLDER STARVATION ON THE PAD OR THE LACK OF A PROPER FILLET.KINDLY CHECK	OPEN	

ID	ISSUES-CATEGORY	PRIORITY	IMAGE	X-LOCATION(")	Y-LOCATION(")	LAYERS	VALUE	ISSUE/ RECOMMENDATION	STATUS	CUSTOMER FEEDBACK
9	NON-PLATED THRU HOLES TOO CLOSE TO COPPER	HOT		0.537062	0.065874	L6;L6		NON-PLATED THRU HOLES TOO CLOSE TO COPPER RUN A RISK OF A STRESS FRACTURE IN THE COPPER OR A "BITE" FROM THE DRILL.	OPEN	
10	SILKSCREEN ON PADS	WARM		0.076746	0.794569	TOPSILK; TOPSILK	0	SILKSCREEN ON PADS WILL CREATE PROBLEMS WITH SOLDER QUALITY	OPEN	
11	COVERAGE	HOT		-1.016788	0.5687	SMB;BOTTOM	0	LINES WHICH PASS CLOSE TO A PAD MUST BE FULLY COVERED BY MASK TO AVOID SOLDER BRIDGING BETWEEN LINE AND PAD DURING THE ASSEMBLY PROCESS. KINDLY CHECK	OPEN	
12	LINES TOO CLOSE TO A PAD	HOT		0.274988	-0.913228	SMT;TOP	0.002	LINES TOO CLOSE TO A PAD MUST BE FULLY COVERED BY MASK TO AVOID SOLDER BRIDGING	OPEN	
13	COMP. WITHOUT REFERENCE DESIGNATOR C39	HOT		-0.440732	0.995835	COMP_+_TOP; SST	0.02	REF DESIGNATOR WAS MISSING FOR C39,CAN CAUSE ERRORS AT RE-WORK.KINDLY CHECK.	OPEN	
14	COPPER SLIVERS	HOT		2.54	5.822874S	BOTTOM	0.0043	SLIVERS CAN CAUSE REPEAT DEFECTS AT FAB DUE TO RESIST FLAKING.KINDLY CHECK	OPEN	
15	ACID TRAPS	WARM		4.28	-11.02	BOTTOM	NA	ACUTE ANGLES CREATE ACID TRAPS, RE ROUTE THESE TRACES TO AVOID ACID TRAPS.KINDLY CHECK.	OPEN	
16	OPEN NET	CRITICAL		AS PER PICTURE	AS PER PICTURE	TOP;BOT	NA	GND_EARTH NET IS OPEN IN THE BOARD, KINDLY CHECK.	OPEN	

ID	ISSUES-CATEGORY	PRIORITY	IMAGE	X-LOCATION(")	Y-LOCATION(")	LAYERS	VALUE	ISSUE/ RECOMMENDATION	STATUS	CUSTOMER FEEDBACK
17	PTH-COPPER	CRITICAL		AS PER PICTURE	AS PER PICTURE	TOP;BOT	NA	WHEN AN ANNULAR RING AROUND A PLATED THROUGH HOLE OR VIA IS TOO SMALL, THE HOLE MAY SHIFT DURING DRILLING AND CAUSE INSUFFICIENT PLATING LATER.FOR COMPONENT THERE WILL NOT BE SUFFICIENT LAND FOR ASSEMBLING AND LEAD TO IMPROPER SOLDER JOINT	OPEN	
18	PASTE	CRITICAL		3.625793	-10.135245	SPT	NA	SOLDER PASTE PAD MISSING FOR Y2 COMPONENT, KINDLY PROVIDE THE PAD FOR COMPONENT	OPEN	
19	REF DES MISPLACED	WARM		9.234	-1.683	SILKTOP; SILKTOP	NA	COMPONENTS WITH MISPLACED REFERENCE DESIGNATORS ON THE SILKSCREEN CAN CAUSE ERRORS AT RE-WORK	OPEN	
20	UNDRILLED AREAS	HOT		-	-	GND;GND	-	UNDRILLED AREAS LARGER THAN A GIVEN SIZE ARE SUSCEPTIBLE TO DELAMINATION		
21	THERMAL PADS MISSING	HOT		2.885024	-9.270029	PWR;PWR	0	THROUGH-HOLE PINS CONNECTED DIRECTLY TO A PLANE WITHOUT A THERMAL MAY CAUSE AN IMPROPER SOLDER JOINT DUE TO HEAT DISSIPATION.	OPEN	
22	MISSING PAD FOR PTH	HOT CRITICAL		2.159449	0.11811	L2 L3;DRILL	0.08661	PAD MISSING FOR PTH DRILL IN INNER LAYERS FOR 2.2MM DRILL SIZE, KINDLY CHECK.	OPEN	